SIEMENS

Course Description

Xpedition
Substrate Integration Xpedition

Course Code	280862-US
Software	Xpedition vx2.14
User Level	All
PricingID	Contact Us
Live Online Duration	6 hours for each day for 3 days

The Substrate Integration using Xpedtion course provides a co-design methodology that allows design teams the ability to easily plan and optimize I/O and connectivity from a chip(s), through multiple packaging scenarios while targeting multiple different printed circuit boards. Using this planning, optimization, and design methodology, engineering teams for the IC, the Package, and the PCB can drive rule-based I/O level optimization and perform ball-out studies from their respective domains, all while visualizing the impact across the complete system.

Hands-on lab exercises will reinforce lecture and discussion topics under the guidance of our industry expert instructors.

PREREQUISITES

Prerequisites

- Familiarity with concepts of package technology
- Familiarity with Windows operating system

PRIMARY COURSE TOPICS

Throughout this course, extensive hands-on lab exercises provide you with practical experience using Xpedition layout software. Hands-on lab topics include:

- User Interface
- Connectivity
- Project Creation
- Part Stacking
- Working with Components
- Working with Customer Library Parts
- Advanced Design Modification and Features
- Layout Routing Unraveling
- Defining and Editing a Virtual Die